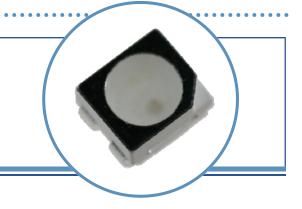
Full Color PLCC4 LED



OVSARGB4R8

- Surface mount device packaged in 8 mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with infrared and vapor phase reflow solder
- Dimensions: 3.5 x 2.8 x 1.9 mm
- 120° viewing angle

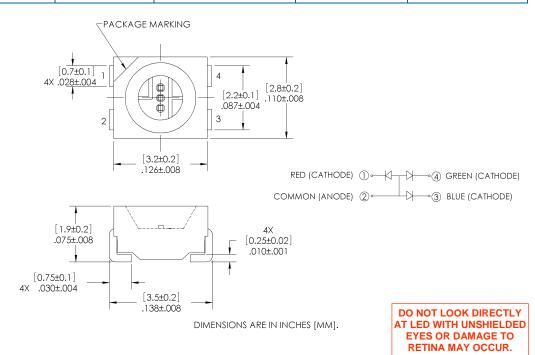


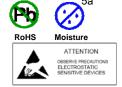
The **OVSARGB4R8** provides full color light output from a single package, 3-die design. This surface mount package is an efficient solution in modular applications that require uniform brightness and color-on-demand. Light output is optimized by an interior reflector and the wide viewing angle adds flexibility for applications ranging from hand-held appliances to automotive interiors.

Applications

- RGB full-color indoor and outdoor displays
- Backlighting
- · Coupling into light guides
- Automotive interiors
- Entertainment equipment

Dort Number		Lana Calar			
Part Number	Type	Material	Emitted Color	Intensity Typ. mcd	Lens Color
OVSARGB4R8	R	AllnGaP	Red	635	Diffused
	G	InGaN	Green	1000	
	В	InGaN	Blue	335	







Absolute Maximum Ratings $T_A = 25^{\circ} C$ unless otherwise noted

DADAMETED		RATING			
PARAMETER	R	G	В	UNIT	
Storage Temperature		-40 ~ +100		°C	
Operating Temperature		-40 ~ +100		°C	
Reverse Voltage		5		V	
Continuous Forward Current (1 chip on)	50	25	25	mA	
Peak Forward Current (10% Duty Cycle, PW ≤ 100 µsec, 1 chip on)	200	100	100	mA	
Power Dissipation	130	100	100	mW	
Junction Temperature	110	110	110	°C	
Junction/ambient (1 chip on)	450	400	450	°C/W	
Junction/ambient (3 chips on)	650	580	680	°C/W	
Junction/solder point (1 chip on)	300	280	300	°C/W	
Junction/solder point (3 chips on)	450	430	480	°C/W	
Electrostatic Discharge Classification (JEDEC-JESD22-A114F)				Class 1C	
Moisture Sensitivity Level (IPC/JEDEC J-STD-020C)		5a / 24 Hrs			

Electrical Characteristics

T_A = 25° C unless otherwise noted

OVMDOL	DADAMETER	VALUES				LINUT	CONDITIONS
SYMBOL	PARAMETER		R	G	В	UNIT	CONDITIONS
1	Luminous Intonsity	Min	450	710	224	mcd	I _F = 20 mA
Ι _V	Luminous Intensity	Тур	635	1000	335		
V	Forward Voltage	Тур	2.0	3.2	3.2	>	I _F = 20 mA
V _F	Forward Voltage	Max	2.6	4.0	4.0		
I_R	Reverse Current (max)		10	10	10	μΑ	V _R = 5 V
λ_{D}	Dominant Wavelength		619-624	520–540	460–475	nm	I _F = 20 mA
2 ⊝½	50% Power Angle		120	120	120	deg	I _F = 20 mA
Δλ	Spectral Radiation Bandwidth		24	38	28	nm	I _F = 20 mA



Standard Bins

LEDs are sorted to luminous intensity (I_V) and dominant wavelength (nm) bins shown. Each reel consists of a single intensity bin and a single color bin. Orders are filled using all intensity and color bins listed in the following tables. Optek will not accept orders for single intensity bins or single color bins.

Luminous Intensity (I_V) @ 20mA

RED				
Code	Min (mcd)	Max (mcd)		
hj	403	505		
J	450	560		
km	505	635		
K	560	710		
np	635	805		
М	710	900		

GREEN				
Code	Min (mcd)	Max (mcd)		
М	710	900		
qr	805	1010		
N	900	1120		
st	1010	1260		
Р	1120	1400		

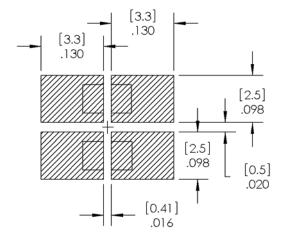
BLUE				
Code	Min (mcd)	Max (mcd)		
F	224	280		
de	252	318		
G	280	355		
fg	318	403		
Н	355	450		

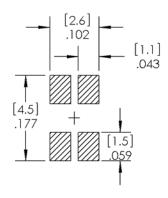
Dominant Wavelength (nm)

	RED	
Code	Min (nm)	Max (nm)
RB	619	624

GREEN			
Code	Min (nm)	Max (nm)	
G7	520	525	
G23	522.5	527.5	
G8	525	530	
G45	527.5	532.5	
G9	530	535	
G67	532.5	537.5	
Ga	535	540	

	BLUE	
Code	Min (nm)	Max (nm)
В3	460	465
B23	462.5	467.5
B4	465	470
B45	467.5	472.5
B5	470	475



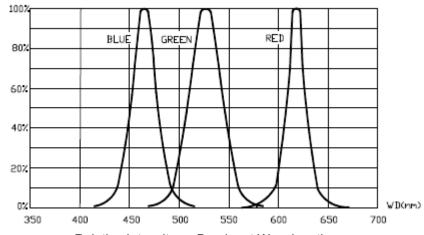


RECOMMENDED SOLDER PASTE PATTERN

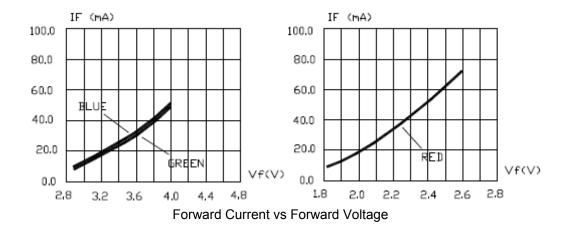
RECOMMENDED COPPER PATTERN

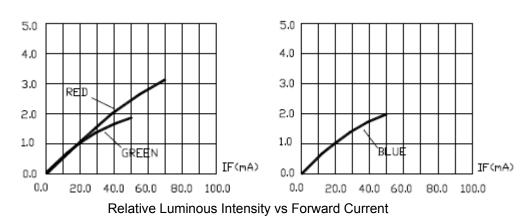


Typical Electro-Optical Characteristics Curves



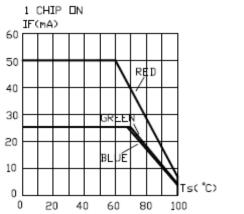
Relative Intensity vs Dominant Wavelength

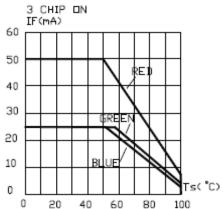




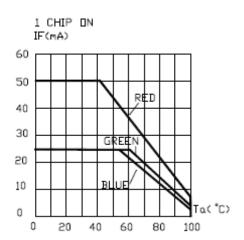


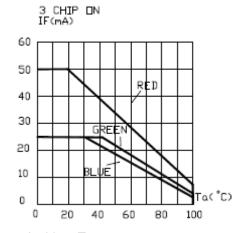
Typical Electro-Optical Characteristics Curves



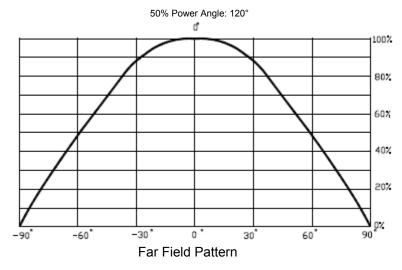


Maximum Forward DC Current vs Solder Point Temperature





Maximum Forward DC Current vs Ambient Temperature

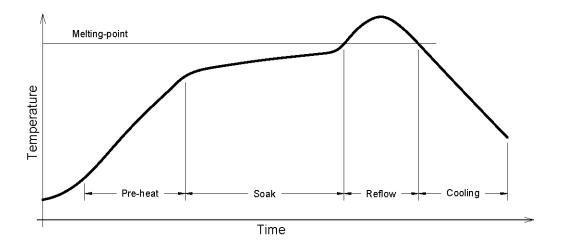




Reflow Solder Profile

Manual soldering by soldering iron:

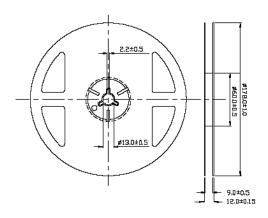
- The use of a soldering iron of less than 25 W is recommended. The temperature of the iron must be kept at below 315°C with soldering time within 2 seconds
- The epoxy resin of the SMD LED should not contact the tip of the soldering iron.
- No mechanical stress should be exerted on the resin portion of the SMD LED during soldering.
- Handling of the SMD LED should be done when the package has been cooled down to below 40°C or less. This is to prevent LED failures due to thermal-mechanical stress during handling.
- The temperature (top surface of the SMD LED) profile is as below:



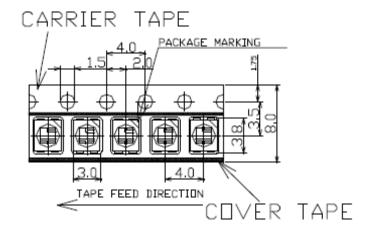
Solder = Lead-Free
Average ramp-up rate = 4°C / sec. max
Preheat temperature: 150 - 200°C
Preheat time: 120 sec. max.
Ramp-down rate = 6°C / sec. max.
Peak temperature = 250°C max.
Time within 5°C of actual peak temperature = 10 sec. max
Duration above 217°C is 60 sec. max



Reel Dimensions: 7-inch reel



Carrier Tape Dimensions: Loaded quantity 2,000 pieces per reel



Moisture Resistant Packaging

